## WHAT IS CLAIMED IS:

Sam Them

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1.	Δ	module,	comprising:	
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- a hermetically-sealable shell having first and second terminal 2 sets; 3
- a first surface acoustic wave (SAW) circuit, located within 4 said shell and couplable to said first terminal set, that filters 5 signals in a first band of communications frequencies; and 6
- a second SAW circuit, located within said shell and couplable 7 to said second terminal set, that filters signals in a second band <u>\_</u> 8 9 of communications frequencies.
  - The module as recited in Claim 1 wherein said first band 2. of communications frequencies comprises a frequency between 800 and 900 megahertz.
  - The module as recited in Claim 1 wherein said second band 3. of communications frequencies comprises a frequency between 1800 2 and 1900 megahertz. 3
  - The module as recited in Claim 1 wherein said shell 4. comprises a common base that supports said first and second SAW 2 3 circuits.

- 5. The module as recited in Claim 1 further comprising a lid coupled to said shell to form a hermetic enclosure that surrounds said first and second SAW circuits.
- 6. The module as recited in Claim 1 wherein said first and second SAW circuits are located on a common piezoelectric substrate.
  - 7. The module as recited in Claim 6 further comprising a crosstalk shield located between said first and second SAW circuits.

A method of manufacturing a circuit module, comprising: 8. providing a hermetically-sealable shell having first and 2 second terminal sets; 3 placing a first surface acoustic wave (SAW) circuit in said 4 shell, said first SAW circuit capable of filtering signals in a 5 first band of communications frequencies; 6 coupling said first SAW circuit to said first terminal set; 7 placing a second SAW circuit in said shell, said second SAW 8 circuit capable of filtering signals in a second band of 9

communications frequencies;

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coupling said second SAW circuit to said second terminal set;

placing a lid on said shell to form an enclosure that surrounds said first and second SAW circuits.

- 9. The method as recited in Claim 8 wherein said first band of communications frequencies comprises a frequency between 800 and 900 megahertz.
- 10. The method as recited in Claim 8 wherein said second band
  2 of communications frequencies comprises a frequency between 1800
  3 and 1900 megahertz.

- 11. The method as recited in Claim 8 wherein said shell comprises a common base that supports said first and second SAW circuits.
- 12. The method as recited in Claim 8 wherein said enclosure 2 is hermetic.
  - 13. The method as recited in Claim 8 wherein said first and second SAW circuits are located on a common piezoelectric substrate.

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14. The method as recited in Claim 13 further comprising forming a crosstalk shield between said first and second SAW circuits.

A module, comprising:

sets;

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2 a hermetically-sealable shell having first and second terminal 3

a first surface acoustic wave (SAW) circuit, located within 4

said shell and couplable to said first terminal set, that filters 5

signals in a first band of communications frequencies;

a second SAW circuit, located within said shell and couplable 7

to said second terminal set, that filters signals in a second band

of communications frequencies; and

a lid coupled to said shell and forming an enclosure that surrounds said first and second SAW circuits.

- The module as recited in Claim 15 wherein said first band 16. of communications frequencies comprises a frequency between 800 and 900 megahertz.
- The module as recited in Claim 15 wherein said second 17. band of communications frequencies comprises a frequency between 1800 and 1900 megahertz.
- The module as recited in Claim 15 wherein said shell 18. comprises a common base that supports said first and second SAW 2 circuits. 3

- 19. The module as recited in Claim 15 wherein said enclosure 2 is hermetic.
- 20. The module as recited in Claim 15 wherein said first and second SAW circuits are located on a common piezoelectric substrate.
  - 21. The module as recited in Claim 20 wherein a crosstalk shield is located between said first and second SAW circuits.